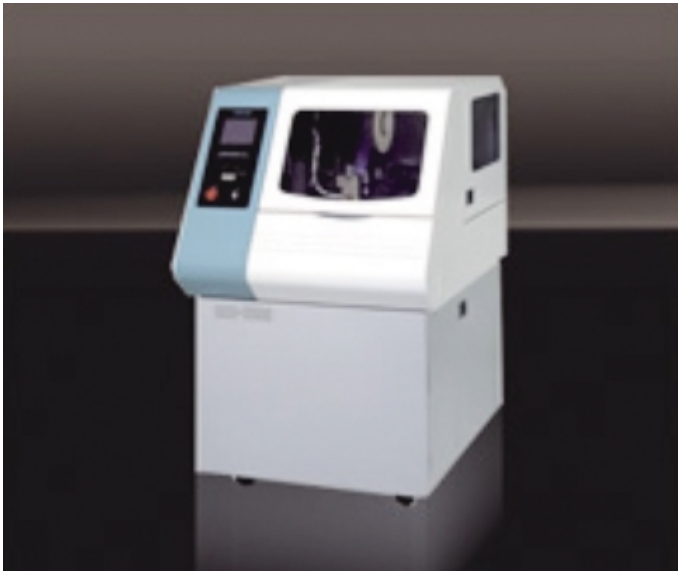


300mm Semi-Automatic BG Tape Remover

RAD-3000m/12R



Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Power consumption	: 0.8kW
Air Supply	Capacity	: 3.0kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)

Applicable Wafer Size 200mm, 300mm

Size Width : 915mm
Depth : 1,080mm
Height : 1,350mm

Weight 250kg

Processing Capacity 30sec/wafer (excludes setting time)

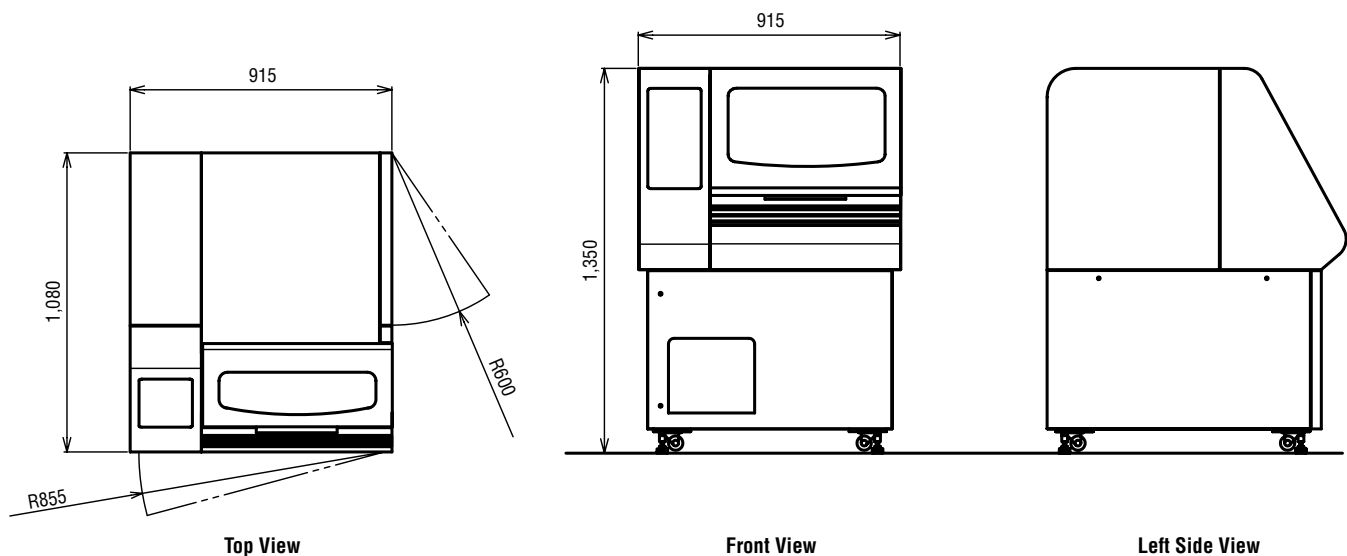
Outline

- Semi-automatic BG Tape remover for mounted wafer.
- Removes back grinding tape by attaching heat seal on the periphery of the wafer, fixed with heater.

Suitable Tapes ·BG Tape : Adwill E series, P series

External View

Unit:mm



LINTEC Corporation *Linking your dreams*

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